



SPECIFICATIONS					
CUSTOMER :	PTC				
SAMPLE CODE :	SH320240T-022-109Q				
MASS PRODUCTION CODE	PH320240T-022-109Q				
SAMPLE VERSION	01				
SPECIFICATIONS EDITION	004				
DRAWING NO. (Ver.)	JLMD-PH320240T-022-109Q_002				
PACKAGING NO. (Ver.)	JPKG-PH320240T-022-I09Q_001				
· · · ·					

Customer Approved

Date:

A	Approved	Checked	Designer
	閆偉	張久慧	劉進
	liminary specification cification for sample a	0	
	Р	OWERTIP TECH. CORP	
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History of Version

Date	Ver.	Edi.	Description	Page	Design by
03/28/2013	01	001	New sample	-	趙冬冬
04/08/2014	01	002	Updating LCM Drawing	-	譚超敏
08/18/2015	01	003	Show Backlight Life Time	9	劉進
01/28/2016	01	004	Update Timing Characteristics	18-23	劉進
				I	Total: 33 Page



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Note : For detailed information please refer to IC data sheet :

Primacy(TFT LCD): SSD2119



1. SPECIFICATIONS

1.1 Features

Main LCD Panel

Item	Standard Value
Display Type	320* (R \ G \ B) * 240 Dots
LCD Type	a-Si TFT , Normally White , TN mode , Transmissive type
Screen size (inch)	3.5 inch
Viewing Direction	6 O'clock
Color configuration	R.G.B. vertical stripe
Backlight	LED B/L
Driver IC	SSD2119 (262K Colors)
Interface	 8/ 9/ 16/ 18-bit 6800-series /8080-series Parallel Interface. Serial Peripheral Interface (SPI). 18-/6-bit RGB interface (DEN,DOTCLK, HSYNC, VSYNC, DB[17:0]). VSYNC interface (system interface + VSYNC). WSYNC interface (system interface + WSYNC).
ROHS	THIS PRODUCT CONFORMS THE ROHS OF PTC Detail information please refer web side : http://www.powertip.com.tw/news.php?area_id_view=1085560481/

1.2 Mechanical Specifications

Item	Standard Value			
Outline Dimension	76.9 (W) * 63.9(L) * 4.75(H)(MAX)	mm		

LCD Panel

Item	Standard Value	Unit
Active Area	70.8 (W) * 53.2 (L)	mm



Touch Panel

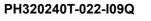
Item	Standard Value	Unit
Outline Dimension (T/P)	76.4(W) * 61.0 (L)	mm
Active Area (T/P)	70.8 (W) * 53.2 (L)	mm

Note : For detailed information please refer to LCM drawing.

1.3 Absolute Maximum Ratings

Module

Item	Symbol	Condition	Min.	Max.	Unit
System Power Supply Voltage	VDDIO	VSS	-0.3	+4.0	V
Input Voltage	VCI		-0.3	+5.0	V
Operating Temperature	Тор	Excluded T/P	-20	+70	°C
Storage Temperature	Tst	Excluded T/P	-30	+80	°C
Storage Humidity	HD	Ta < 60 °C	20	90	%RH



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1.4 DC Electrical Characteristics

Module				VSS	5 = 0V, Ta = 2	5°C
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	VDDIO	-	3.0	3.3	3.6	V
Input High Voltage	VIH1	-	0.8*VDDIO	-	VDDIO	V
Input Low Voltage	VIL1	-	0	-	0.2*VDDIO	V
Output High Voltage	Vон1	IOH=-0.1mA	0.9*VDDIO	-	VDDIO	V
Output Low Voltage	Vol1	IOL=0.1mA	0	-	0.1*VDDIO	V
Supply Current	Іоо	VDDIO = 3.3V		7.5	11.5	mA

1.5 Optical Characteristics

TFT LCD Panel

VDDIO =3.3V, Ta=25°C

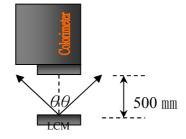
						,		
Item		Symbol	Condition	Min.	Тур.	Max.	Unit	-
Response time		Tr + Tf	-	-	30	45	ms	Note2
	Тор	θY+	00 > 10	-	60	-		
	Bottom	θY-		-	60	-	Dog	Note4
Viewing angle	Left	θХ-	CR ≥ 10	-	60	-	Deg.	Note4
	Right	θX+		-	60	-		
Contrast ratio		CR	-	500	600	-	-	Note3
	White	Х		0.26	0.31	0.36		
		Y		0.28	0.33	0.38		
	Ded	Х		0.58	0.63	0.68		
Color of CIE Coordinate	Red	Y		0.29	0.34	0.39		Noto1
Color of CIE Coordinate		Х		0.29	0.34	0.39		Note1
	Green	Y		0.55	0.60	0.70		
	Blue	Х		0.10	0.15	0.20		
	Diue	Y		0.04	0.09	0.14		
Average Brightness Pattern=white display		IV	IF= 20 mA	162	187	-	cd/m ²	Note1
Uniformity		∆B		70	-	-	%	Note1

Note1:

- $1 : \triangle B = B(min) / B(max) \times 100\%$
- 2 : Measurement Condition for Optical Characteristics:
 - a : Environment: 25°C ±5°C / 60±20%R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
 b : Measurement Distance: 500 ± 50 mm , (θ= 0°)
 c : Equipment: TOPCON BM-7 fast , (field 1°) , after 10 minutes operation.

 - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%





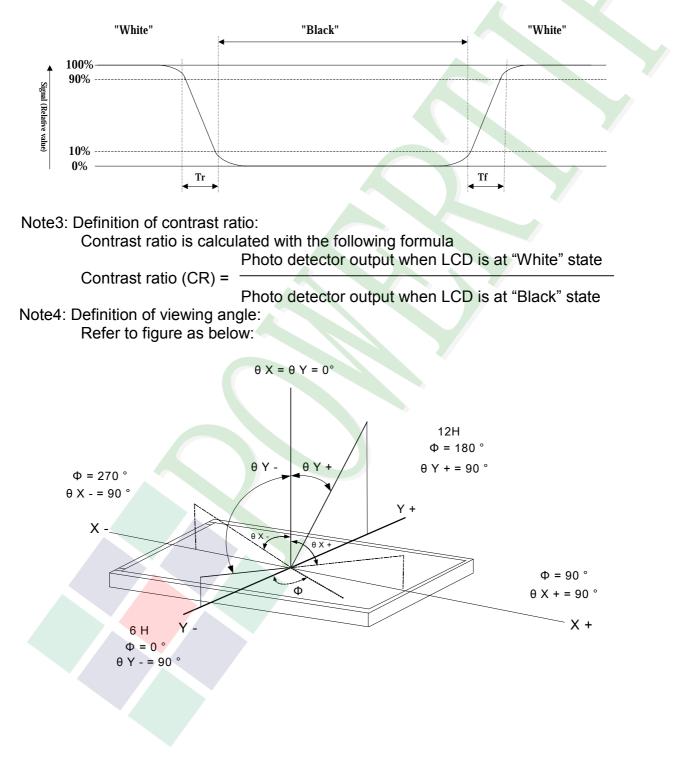
Colorimeter=BM-7 fast



Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white"(falling time) and from "white" to "black"(rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:





1.6 Backlight Characteristics

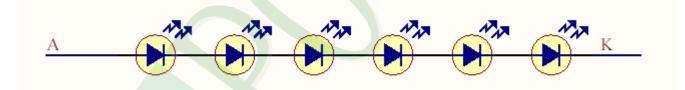
Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
LED Forward Current	IF	Ta =25℃	-	40	mA
LED Reverse Voltage	VR	Ta =25℃	-	21	V

Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF		17.4	19.2	21	V
Average Brightness (Without LCD &T/P)	IV	lf=20mA	4500	5200	-	cd/m ²
CIE Color Coordinate	Х		0.28	0.30	0.32	
(Without LCD &T/P)	Y		0.28	0.30	0.32	-
Color			White			

Internal Circuit Diagram



Other Description

Item	Conditions	Description
Life Time	Ta =25℃ IF= 20mA	20000 hrs



1.7 Touch Panel Characteristics

Touch Panel General Standard Specification

Item	Specification
Input Method	Finger or stylus pen
Operating Temperature Range	-20℃~70℃.
Storage Temperature Range	-30°C~80°C.
Operation Humidity	90%RH or less.
Storage temperature	90%RH or less
Surface Hardness	≥3H.
Pen Sliding Durability	≥1,000,000 times.
Light Transparency	80% min.
Linearity	Less than 1.5%
Resistance Between Terminals.	Direction X (Film side): $200\Omega \sim 900\Omega$. Direction Y (Glass side): $200\Omega \sim 900\Omega$.
Operating Voltage	10V DC max
Operating force	20g~80g



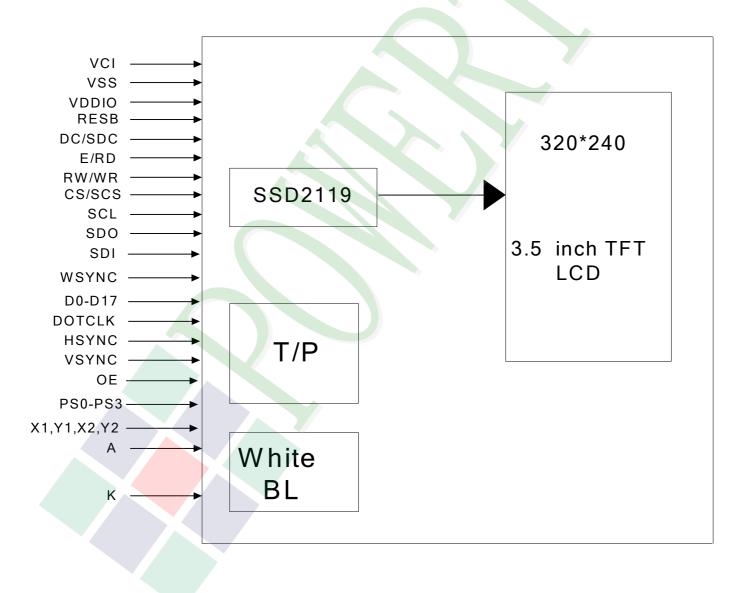
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram



POWERTIP

2.2 Interface Pin Description

Pin No	Symbol	Function
1	VCI	Booster input voltage pin.
2	VCI	Booster input voltage pin.
3	VSS	System ground pin of the IC.
4.	VDDIO	Voltage input pin for logic I/O.
5	VSS	System ground pin of the IC.
6	RESB	System reset pin. - An active low pulse at this pin will reset the IC, Connect to VDDIO in normal operation.
7	DC/SDC	Data or command. DC: Parallel Interface. SDC: Serial Interface.
8	E/RD	6800-system:E(enable signal). 8080-system:RD(read strobe signal). Serial mode: Not used and should be connected to VDDIO or VSS.
9	RW/WR	6800-system: RW(indicates read cycle when High, write cycle when Low). 8080-system: WR(write strobe signal).
10	CS/SCS	CS: Chip Select pin for 6800/8080 Parallel Interface. SCS: Chip select pin for Serial Mode Interface.
11	SCL	Serial clock input.
12	SDO	Data output pin in serial interface.
13	SDI	Data input pin in serial interface.
14	WSYNC	Ram Write Synchronization output. -Leave it OPEN when not used.
15	D17	
16	D16	
17	D15	For parallel mode,8/9/16/18 bit interface. Unused pins should connect to VSS.
18	D14	
19	D13	



Pin No	Symbol	Function
20	D12	
21	D11	
22	D10	
23	D9	
24	D8	
25	D7	For parallel mode,8/9/16/18 bit interface.
26	D6	Unused pins should connect to VSS.
27	D5	Please refer to Table 1.
28	D4	
29	D3	
30	D2	
31	D1	
32	D0	
33	VSS	System ground pin of the IC.
34	DOTCLK	Dot-clock signal and oscillator source.
35	HSYNC	Line Synchronization input.
36	VSYNC	Frame/Ram Write Synchronization input.
37	OE	Display enable pin from controller.
38	VSS	System ground pin of the IC.
39	PS0	
40	PS1	Please refer to Table 1.
41	PS2	
42	PS3	
43	VSS	System ground pin for the IC.
44	X1	Touch screen.
45	Y1	Touch screen.



Pin No	Symbol	Function	
46	X2	Touch screen.	
47	Y2	Touch screen.	
48	VSS	System ground pin for the IC.	
49	К	Backlight LED's cathode.	
50	A	Backlight LED's anode.	

Table 1

Tab	ole 1				
PS3	PS2	PS1	PS0	Interface Mode	Data bus input
0	0	0	0	16-bit 6800 parallel interface.	D[17:10],D[8:1]
0	0	0	1	8-bit 6800 parallel interface.	D[17:10]
0	0	1	0	16-bit 8080 parallel interface.	D[17:10],D[8:1]
0	0	1	1	8-bit 8080 parallel interface.	D[17:10]
0	1	0	0	9-bit generic D[17:9] (262k color) + 3-wire SPI If 65K color, D12 shorts to D17 internally.	-
0	1	0	1	16-bit generic (262k color)+ 3-wire SPI.	-
0	1	1	0	18-bit generic (262k color)+ 3-wire SPI.	-
0	1	1	1	6-bit generic D[17:12] (262k color) + 3-wire SPI.	-
1	0	0	0	18-bits 6800 parallel interface.	D[17:0]
1	0	0	1	9-bits 6800 parallel interface.	D[17:9]
1	0	1	0	18-bit 8080 parallel interface.	D[17:0]
1	0	1	1	9-bit 8080 parallel interface.	D[17:9]
1	1	1	0	3-wire SPI.	-
1	1	1	1	4-wire SPI.	-



2.2.1 Refer Initial code void Initial_Main(void) // For SSD2119

<u>۲</u>	
1	

WriteCOM_Main(0x00,0x28); //VCOM OTP
WriteDAT_Main(0x00,0x06);
WriteCOM_Main(0x00,0x00); //OSCEN=1
WriteDAT_Main(0x00,0x01);
WriteCOM_Main(0x00,0x01); //Driver Output Control
WriteDAT_Main(0x32,0xef); //0X32,0XEF
WriteCOM_Main(0x00,0x02);
WriteDAT_Main(0x04,0x00); //00 00
WriteCOM_Main(0x00,0x03);
WriteDAT_Main(0x60,0x64); //60
WriteCOM_Main(0x00,0x10); //Sleep=0
WriteDAT_Main(0x00,0x00);
WriteCOM_Main(0x00,0x11);
WriteDAT_Main(0x64,0x30);//0X68,0X70 //64,30 07/15
//64 30
WriteCOM_Main(0x00,0x07);
WriteDAT_Main(0x00,0x33);
WriteCOM_Main(0x00,0x25); //Frame frequency=70HZ
WriteDAT_Main(0xd0,0x00);
WriteCOM_Main(0x00,0x0B); //Frequency
WriteDAT_Main(0x53,0x08);
// Adjust the Gamma Curve
WriteCOM_Main(0x00,0x30);
WriteDAT_Main(0x00,0x00);
WriteCOM_Main(0x00,0x31);
WriteDAT_Main(0x01,0x01);



WriteCOM Main(0x00,0x32); WriteDAT Main(0x01,0x00); WriteCOM Main(0x00,0x33); WriteDAT Main(0x07,0x07); WriteCOM_Main(0x00,0x34); WriteDAT Main(0x07,0x07); WriteCOM_Main(0x00,0x35); WriteDAT_Main(0x03,0x05); WriteCOM Main(0x00,0x36); WriteDAT_Main(0x07,0x07); WriteCOM_Main(0x00,0x37); WriteDAT_Main(0x02,0x01); WriteCOM Main(0x00,0x3a); WriteDAT Main(0x12,0x00); WriteCOM Main(0x00,0x3b); WriteDAT Main(0x09,0x00); -----power on sequence WriteCOM Main(0x00,0x0c); WriteDAT Main(0x00,0x04); //0X03 Delay(5000); WriteCOM Main(0x00,0x0d); WriteDAT_Main(0x00,0x09); //0X09 Delay(5000); WriteCOM Main(0x00,0x1e); WriteDAT_Main(0x00,0x68); Delay(5000); WriteCOM Main(0x00,0x0e); WriteDAT_Main(0x27,0x00); //27 Delay(5000);

//-



WriteCOM_Main(0x00,0x26); WriteDAT_Main(0x7c,0x00); WriteCOM_Main(0x00,0x27); WriteDAT_Main(0x00,0x6d); }

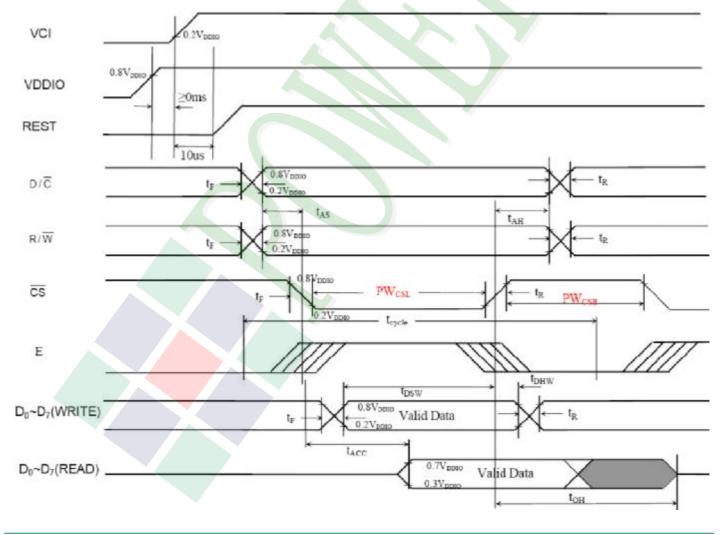


2.3 Timing Characteristics

2.3.1 6800 Interface Timing

Ta= -20 to 70 °C \rightarrow VDDIO = 3.0 to 3.6V

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time (write cycle)	75	-	-	ns
t _{cycle}	Clock Cycle Time (read cycle) (Based on VOL/VOH = 0.3*VDDIO/0.7*VDDIO)	450	4		ns
tAS	Address Setup Time (R/W)	0	-	-	ns
tAH	Address Hold Time (R/W)	0	-	-	ns
tosw	Data Setup Time (D0~D7, WRITE)	5		•	ns
t _{DHW}	Data Hold Time (D0~D7, WRITE))	5	-		ns
tacc	Data Access Time (D0~D7, READ)	200	-		ns
ton	Output Hold time (D0~D7, READ)	100		•	ns
PWCSL	Pulse width /CS low (write cycle)	40	1	-	ns
PWCSH	Pulse width /CS high (write cycle)	25		-	ns
PWcsL	Pulse width /CS low (read cycle)	225		-	ns
PWCSH	Pulse width /CS high (read cycle)	225	-	-	ns
t _R	Rise time		-	15	ns
tF	Fall time		-	15	ns



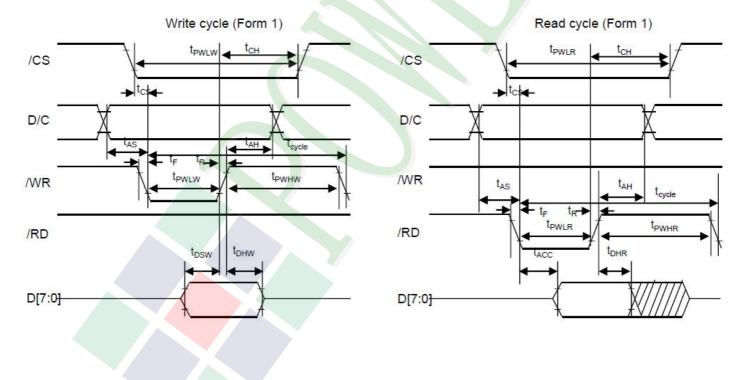


2.3.2 8080 Interface Timing

Symbol	Parameter	Min	Тур	Max	Unit
teyele	Clock Cycle Time (write cycle)	100		-	ns
tas	Address Setup Time	10			ns
t _{AH}	Address Hold Time	0		7	ns
tcs	Chip Select Time	0	1946		ns
t _{CH}	Chip Select Hold Time	0			ns
tosw	Write Data Setup Time	10	1270	-	ns
tDHW	Write Data Hold Time	10	1.	-	ns
t _{DHR}	Read Data Hold Time	100	-	-	ns
tACC	Access Time (RAM)	250	123		ns
172536402-52	Access Time (command)	250	243	-	ns
TPWLR	Chip Select Low Pulse Width (read RAM)	500	-		ns
t PWLR	Chip Select Low Pulse Width (read Command)	500	121	1.2	ns
t PWLW	Chip Select Low Pulse Width (write)	50			ns
T PWHR	Chip Select High Pulse Width (read)	500		-	ns
t _{PWHW}	Chip Select High Pulse Width (write)	50	-		ns
t _R	Rise Time	-		15	ns
tF	Fall Time		1.12	15	ns

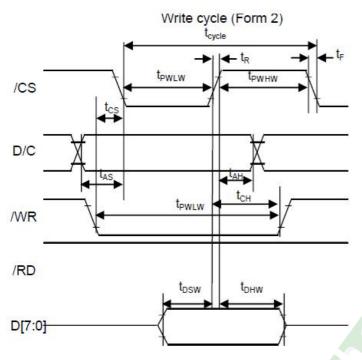
Note: All timings are based on 20% to 80% of VDDIO-VSS

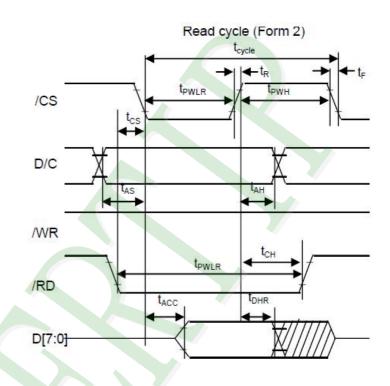
Form 1: /CS low pulse width > /WR low pulse width



POWERTIP

Form 2: /CS low pulse width < /WR low pulse width



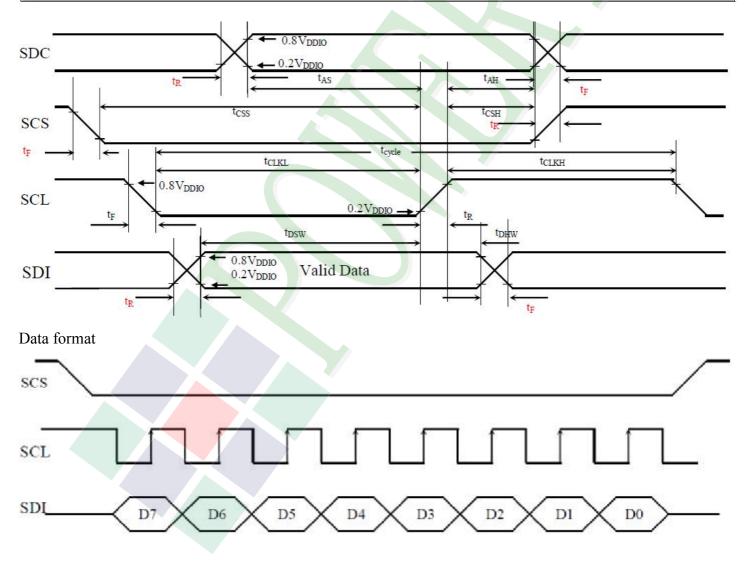




2.3.3 Serial Interface Timing

Ta= -20 to 70 °C , VDDIO = 3.0 to 3.6V

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	77	1	-	ns
fclk	Serial Clock Cycle Time SPI Clock tolerance = +/- 2 ppm	-	-	15	MHz
tAS	Register select Setup Time	4	-	-	ns
t _{AH}	Register select Hold Time	5			ns
tcss	Chip Select Setup Time	2		-	ns
t _{CSH}	Chip Select Hold Time	10		(.	ns
t _{DSW}	Write Data Setup Time	5		-	ns
t _{OHW}	Write Data Hold Time	10	-	•	ns
t _{CLKL}	Clock Low Time	38	1431		ns
t CLKH	Clock High Time	38	120	-	ns
t _R	Rise time	-	-	15	ns
t _F	Fall time	-	-	15	ns





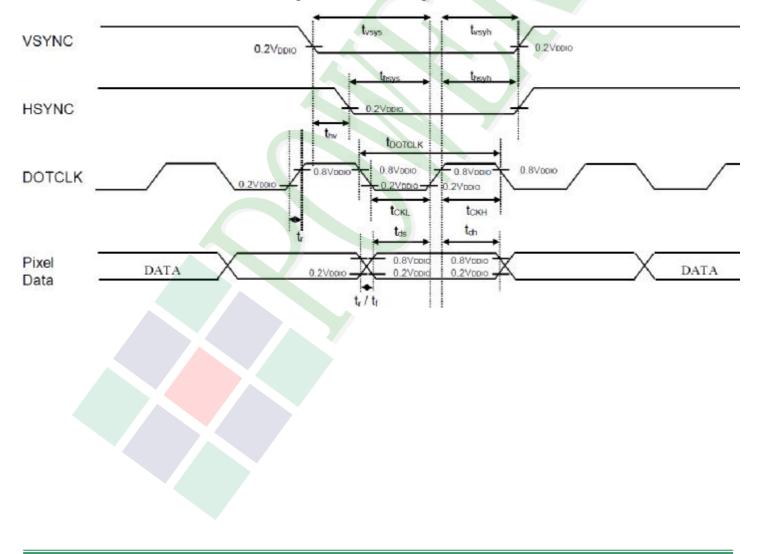
2.3.4 RGB Interface Timing

Ta= -20 to 70 °C , VDDIO = 3.0 to 3.6V

Symbol	Parameter	Min	Тур	Max	Unit
f DOTCLK	DOTCLK Frequency (70Hz frame rate)	1	5.5	8.2	MHz
t DOTCLK	DOTCLK Period	122	182	1000	ns
tysys	Vertical Sync Setup Time	20	-	-	ns
tvsyh	Vertical Sync Hold Time	20		-	ns
tHSYS	Horizontal Sync Setup Time	20	27	-	ns
t _{HSYH}	Horizontal Sync Hold Time	20	-	-	ns
t _{HV}	Phase difference of Sync Signal Falling Edge	0	-	HFP-1	t DOTCLK
tCLK	DOTCLK Low Period	61	1.0	-	ns
tскн	DOTCLK High Period	61	-	-	ns
t _{DS}	Data Setup Time	25	(-)	-	ns
tDH	Data hold Time	25	s=:	-	ns

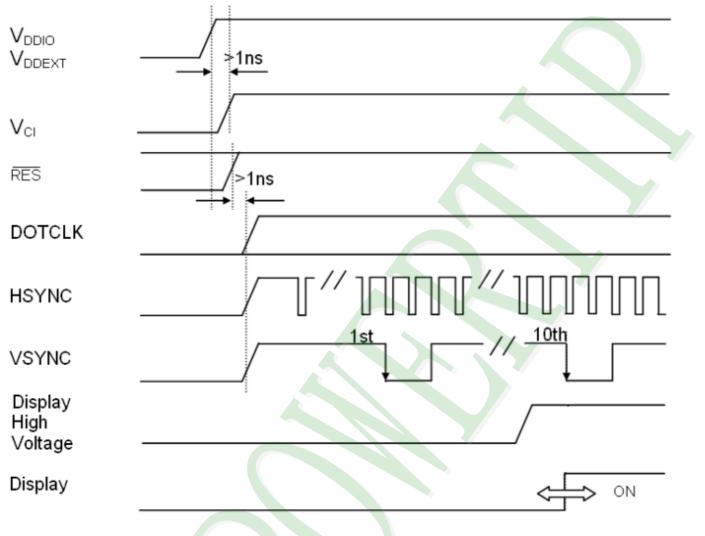
Note: External clock source must be provided to DOTCLK pin of SSD2119AM1. The driver will not operate in absence of the clocking signal.

*HFP: Horizontal Front Porch setting in customers' setup





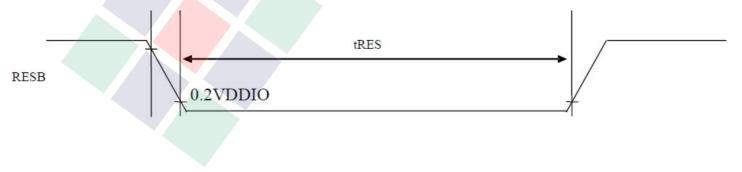
Power Up Sequence for RGB mode



2.3.5 Reset Timing

Ta= -20 to 70 °C $\,$ $\,$ VDDIO = 3.0 to 3.6V

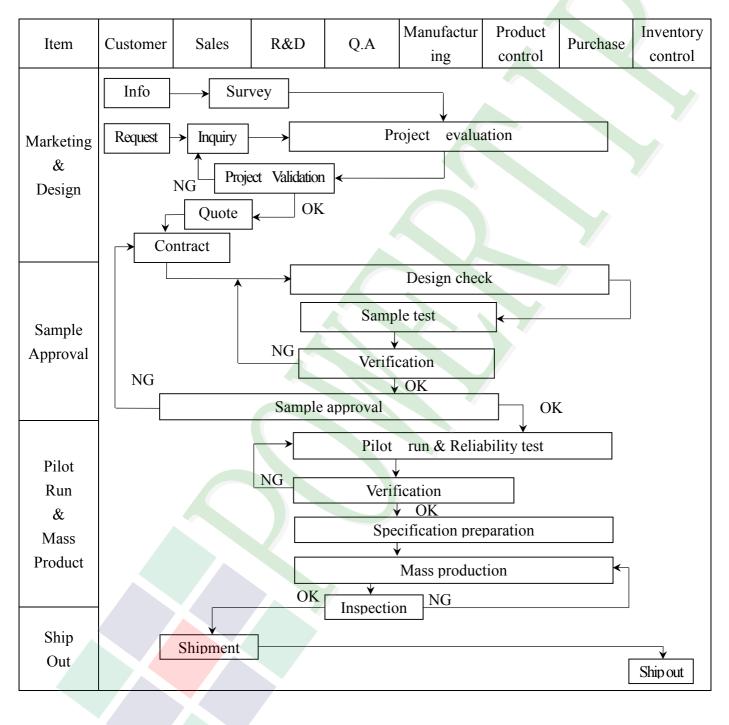
Symbol	Parameter	Min	Тур	Max	Unit
t _{RES}	Reset pulse duration	15	-	5 	us





3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart





Item	Customer	Sales	R&D	Q.A	Manufactu ring	Product control	Purchase	Inventory control
Sales Service	Info	→ Claim sis report	[Trackin	Failure and Corrective			
Q.A Activity	 ISO 9001 Equipme: Standardi 		n		ocess improv Education An	d Training		



3.2. Inspection Specification

Scope : The document shall be applied to TFT-LCD Module for 3. 5" ~10" (Ver.B01).

◆Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.

◆Equipment : Gauge、MIL-STD、Powertip Tester、Sample

◆Defect Level : Major Defect AQL : 0.4 ; Minor Defect AQL : 1.5

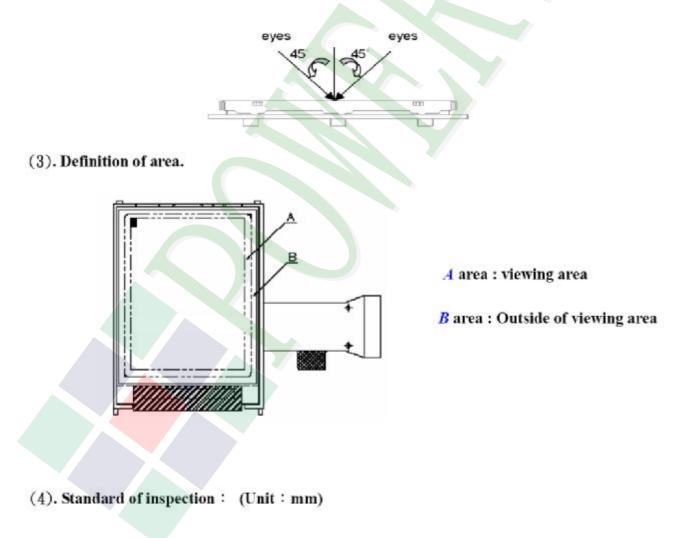
♦OUT Going Defect Level : Sampling.

Standard of the product appearance test :

a. Manner of appearance test :

(1). The test best be under 20W×2 fluorescent light · and distance of view must be at 30 cm.

(2). The test direction is base on about around 45° of vertical line.



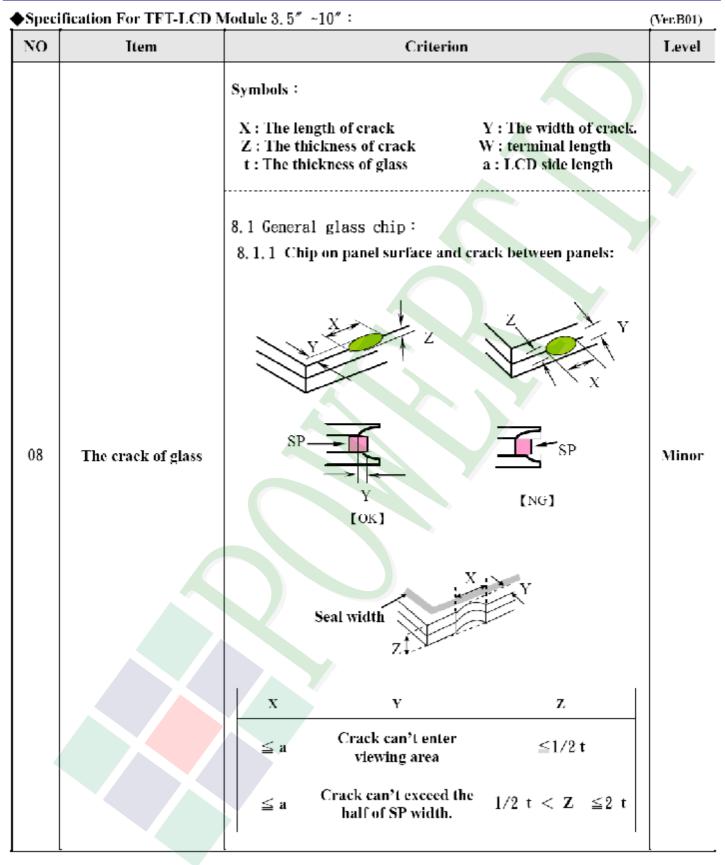


♦Spe	cification For TFT-L	CD Module 3, 5″	~10″:		(Ver.B01)	
NO	Item	Criterion			Level	
		1. 1The part nur production.		t with work order of	Major	
01	01 Product condition	1. 2 Mixed product types.				
	1. 3 Assembled in inverse direction.					
02	Quantity	2. 1 The quantity is inconsistent with work order of production.			n. Major	
03	Outline dimension	3.1 Product dimension and structure must conform to structure diagram.			ucture Major	
		4.1 Missing line	character and icon	n.	Major	
		4. 2 No function or no display.				
04	Electrical Testing	4. 3 Display malfunction.				
		4. 4 LCD viewing angle defect.				
		4, 5 Current con	sumption exceeds	product specifications.	Major	
				1		
			Item	Acceptance (Q'ty)		
	Dot defect		Bright Dot	≦ 4		
		Dot	Dark Dot	≦ 5		
	(Bright dot \	Defect	Joint Dot	≦ 3		
05	Dark dot) On -display 5.		Total	≦ 7	Minor	
		5.1 Inspection]	pattern : full white	e , full black , Red , Gree	n and	
			blue scree	ns.		
		5.2 It is defined	as dot defect if def	ect area >1/2 dot.		
		5, 3 The distance between two dot defect ≥ 5 mm.				

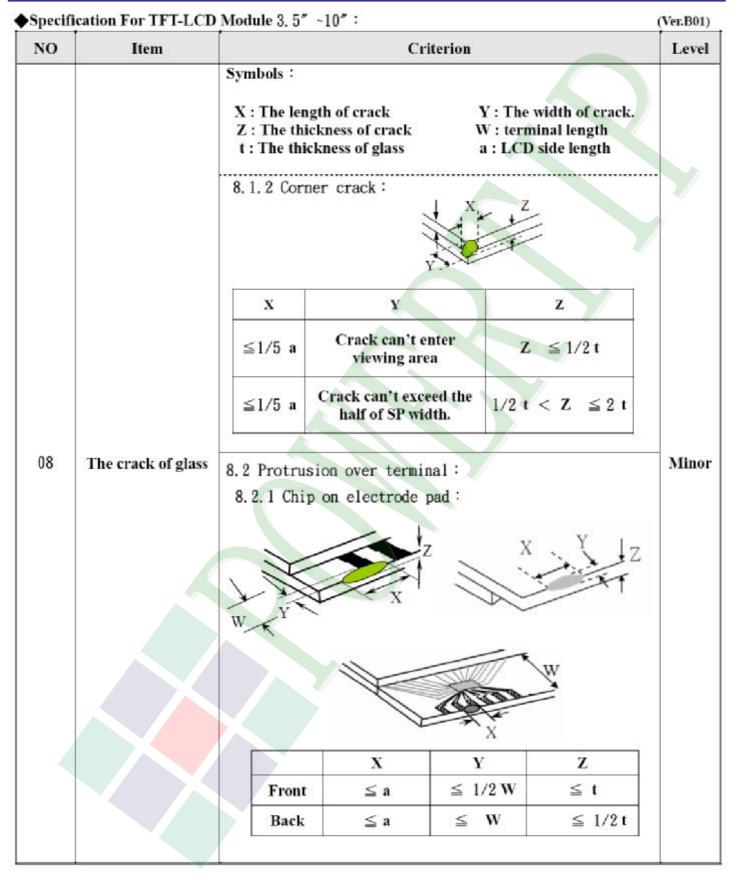


♦ Specii	fication For TFT-LCI	Module 3. 5″~10″:		(Ver.B01)	
NO	Item	Criterion			
	6.	1 Round type (Non-display or display) :			
		Dimension (diameter ÷ Φ) Acceptance	ce (Q'ty) B area		
	Black or white dot \scratch \s	$\Phi \leq 0.25$ Ignore			
	contamination	$0.25 < \Phi \le 0.50$ 5			
	Round type	$\Phi > 0.50$ 0	Ignore		
		Total 5			
06	$\Phi = (\mathbf{x} + \mathbf{y}) / 2$	2 Line type(Non-display or display) :		Minor	
	Line type	Length (L) Width (W) A ar	ptance (Q'ty) 'ea Barea		
		W ≦ 0.03 Igno	ne		
		$L \le 10.0$ 0.03 < W ≤ 0.05 4			
		L ≤ 5.0 0.05 < W ≤ 0.10 2	Ignore		
		Total 5			
		Dimension (diameter : Φ) Acceptance A area	B area		
		$\Phi \leq 0.25$ Ignore			
07	Polarizer	$0.25 < \Phi \le 0.50$ 4		Minor	
	Bubble	$0.50 < \Phi \le 0.80$ 1	Ignore		
		$\Phi > 0.80$ 0			
		Total 5			
L				<u> </u>	

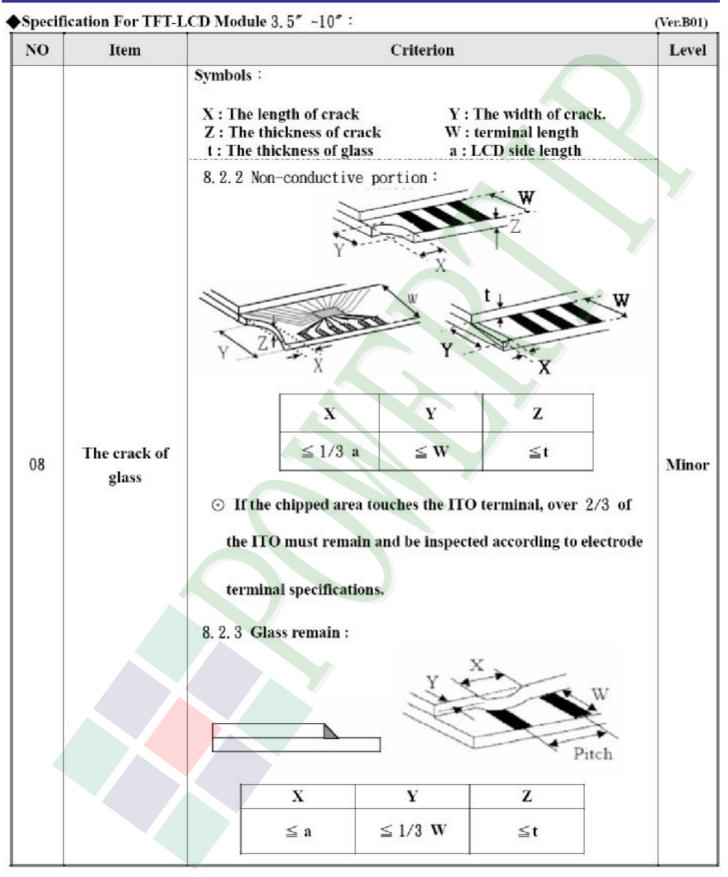














4. RELIABILITY TEST

4.1 Reliability Test Condition

(VER.B01)

NO.	TEST ITEM	TEST CONDITION				
1	High Temperature	Keep in 80°℃ ±2°℃ 96 hrs				
T	Storage Test	Surrounding temperature, then storage at normal condition 4hrs.				
2	Low Temperature	Keep in -30° C $\pm 2^{\circ}$ C 96 hrs				
_	Storage Test	Surrounding temperature, then storage at normal condition 4hrs.				
3	High Temperature /	Keep in +60 °C /90% R.H duration				
	High Humidity Storage Test	Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)				
	Storage 10st		\rightarrow +80°C \rightarrow +25°C			
		(30mins) (5mins)	(30mins) (5mins)			
4	Temperature Cycling		Cycle			
	Storage Test		storage at normal condition 4hrs.			
		Air Discharge:	Contact Discharge:			
		Apply 2 KV with 5 times	Apply 250 V with 5 times			
		Discharge for each polarity +/-	discharge for each polarity +/-			
		1. Temperature ambiance : 15° C ~ 35° C				
5	ESD Test	2. Humidity relative : $30\% \sim 60\%$				
		3. Energy Storage Capacitance(Cs+Cd) : 150pF±10%				
		 4. Discharge Resistance(Rd) : 330Ω±10% 5. Discharge, mode of operation : 				
		Single Discharge (time between successive discharges at least 1 sec				
		(Tolerance if the output voltage in	6			
		1. Sine wave $10 \sim 55$ Hz frequence	,			
6	Vibration Test	2. The amplitude of vibration :1.				
	(Packaged)	3. Each direction $(X \cdot Y \cdot Z)$ due				
		Packing Weight (Kg	Drop Height (cm)			
7		0 ~ 45.4	122			
	Drop Test	45.4 ~ 90.8	76			
	(Packaged)	90.8 ~ 454	61			
		Over 454	46			
		Drop Direction : %1 corner / 3 edg	es / 6 sides each 1 time			
		I DIOD DIFECTION : WI COFNER / 3 Edg	es / 0 sides each ±thile.			



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully, do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth , as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is $25^{\circ}C \pm 5^{\circ}C$ and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush , shake , or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.

